

APPEAL BRIEF UNDER 37 C.F.R. § 41.37

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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Huy T. Vo

Examiner: Son Luu Mai

Serial No.: 09/808,750

Group Art Unit: 2827

Filed: March 15, 2001

Docket: 303.723US1

For: DEVICE AND METHOD TO REDUCE WORDLINE RC TIME CONSTANT IN
SEMICONDUCTOR MEMORY DEVICES

APPEAL BRIEF UNDER 37 CFR § 41.37

Mail Stop Appeal Brief - Patents
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The Appeal Brief is presented in support of the Notice of Appeal to the Board of Patent Appeals and Interferences, filed on April 30, 2006, from the Final Rejection of claims 1-41 and 45-57 of the above-identified application, as set forth in the Final Office Action mailed on January 30, 2006.

The Commissioner of Patents and Trademarks is hereby authorized to charge Deposit Account No. 19-0743 in the amount of \$500.00 which represents the requisite fee set forth in 37 C.F.R. § 41.2(b)(2). The Appellant respectfully requests consideration and reversal of the Examiner's rejections of pending claims.

1. REAL PARTY IN INTEREST

The real party in interest of the above-captioned patent application is the Assignee, Micron Technology, Inc.

2. RELATED APPEALS AND INTERFERENCES

There are no appeals or interferences known to Appellant.

3. STATUS OF THE CLAIMS

The present application was filed on March 15, 2001 with claims 1-54. In the first Office Action, claims 1-54 were rejected. In a response to this Office Action filed August 21, 2002, claims 1, 8, 15, 19, 26, 30, 37, 42, 45, and 49 were amended. No claims were canceled. A first Final Office Action (which was the second office action) was mailed October 18, 2002 that rejected claims 1-54. A response to the first Final Office Action filed December 18, 2002 did not amend or cancel any claims. An Advisory Action mailed January 24, 2003 indicated that the application was not in condition for allowance. A Request for Continued Examination was filed February 19, 2003 along with amendments to claims 1, 5, 8, 15, 19, 26, 30, 37, 42, 45, and 49. No claims were canceled.

A third Office Action was mailed March 7, 2003 rejecting claims 1-54. A response to the third Office Action mailed June 9, 2003 did not amend or cancel any claims. A second Final Office Action (which was the fourth office action) was mailed June 25, 2003 that rejected claims 1-54. In a response to the second Final Office Action filed August 25, 2003, claims 1, 5, 8, 15, 19, 26, 30, 37, 42, 45, and 49 were amended. No claims were canceled. An Advisory Action was mailed October 6, 2003 that indicated the application was not in condition for allowance because the amendments raise new issues that would require further consideration and/or searching. A Request for Continued Examination was filed October 15, 2003 to have the Examiner consider the amendments.

A fifth Office Action was mailed December 10, 2003 rejecting claims 1-54. A response to the fifth Office Action was filed March 10, 2004 that amended claims 1, 5, 8, 15, 19, 26, 30, 37, 45, and 49. Claims 42-44 were canceled. Claims 1-41 and 45-54 were pending in the application. A third Final Office Action was mailed May 21, 2004 that rejected claims 1-41 and 45-54. In a response to the third Final Office Action filed July 21, 2004, claims 1, 5, 8, 15, 19, 26, 30, 37, 45, and 49 were amended. No claims were canceled. An Advisory Action was mailed August 12, 2004 that indicated the application

was not in condition for allowance because the amendments raised new issues that required further consideration and/or searching. A Request for Continued Examination was filed August 23, 2004 to have the Examiner consider the amendments.

A seventh Office Action was mailed October 19, 2004 rejecting claims 1-41, 45-54. A response to the seventh Office Action was filed March 10, 2004 that amended claims 1, 5, 8, 15, 19, 26, 30, 37, 45, and 49. No claims were canceled. A fourth Final Office Action was mailed April 15, 2006 that rejected claims 1-41 and 45-54. In a response to the fourth Final Office Action filed June 15, 2005, claims 1, 5, 8, 15, 19, 26, 30, 37, 45, and 49 were amended. No claims were canceled. An Advisory Action was mailed July 5, 2005 that indicated the application was not in condition for allowance because the amendments raised new issues that required further consideration and/or searching. A Request for Continued Examination was filed July 12, 2005 to have the Examiner consider the amendments.

A ninth Office Action was mailed August 26, 2005 rejecting claims 1-41, 45-54. A response to the seventh Office Action was filed November 28, 2005 that amended claims 1, 5, 8, 15, 19, 26, 30, 37, 45, and 49. No claims were canceled. A Supplemental Amendment was filed December 5, 2006 adding claims 55-57. Claims 1-41, 45-57 were pending in the application. A fifth Final Office Action was mailed January 30, 2006 that rejected claims 1-41 and 45-57.

Thus, claims 1-41, 45-57 stand rejected and remain pending.

4. STATUS OF AMENDMENTS

No amendments have been made subsequent to the Final Office Action which was mailed January 30, 2006.

5. SUMMARY OF CLAIMED SUBJECT MATTER

As noted in the background section of the present patent application, the performance of a dynamic random access memory (DRAM) is largely dependent on the resistance of the DRAM circuitry. A lower resistance in the circuit leads to a lower value of a resistance-capacitance (RC) time constant, and a faster performing memory device. The RC time constant is especially affected by wordline design due to the extended length of word lines, and their necessarily small size as they are integrated into access transistors. In ultra large scale integrated (ULSI) circuits, a highly conductive word line is necessary to improve circuit density and performance. It therefore follows, that the problem of wordline RC losses must be overcome. As devices are scaled down in size, word line widths are also decreased. Both the smaller cross section of wordlines, and the increased length of wordlines in ULSI circuits contribute to increased resistance (pg. 1 line 18 to pg. 2 line 7).

Wordlines are frequently made of polysilicon, however polysilicon has a relatively high resistivity compared to other metal materials. One approach to lowering wordline resistivity has been to add a second layer of lower resistivity metal on top of a polysilicon wordline to make a two layer wordline. The aim of this approach is to lower the resistivity of the entire wordline, and as a result to accommodate the large number of memory cells that a wordline must access in a ULSI circuit. A significant problem with this approach has been the compatibility of the polysilicon with the second metal layer. They tend to diffuse into each other, and the low resistivity of the metal layer is drastically compromised (pg. 2 lines 10–17).

The present application describes memory arrays, memory devices, integrated circuits, information handling devices, methods of reducing a wordline RC time constant, and methods of forming a memory device. A memory array taught by Appellant and claimed in claims 1-4 includes a strapping line of lower resistance than the wordlines coupled to a single continuous wordline in a single array. The strapping line bypasses only a portion in a middle region between a first and second end of the single continuous

wordline, and bypasses only a portion of a wordline within the single memory array. The memory array also includes at least two channels connecting the strapping line to a first and second end of the portion of the single continuous wordline (FIG. 5 and pg. 6 line 20 to pg. 7 line 10). An integrated circuit having such a memory array is claimed in claims 15-18. An information handling device having such a memory array is taught and claimed in claims 26-29 (pg. 5 lines 8-9, pg. 6 lines 14-16, pg. 6 line 20 to pg. 7 line 10).

A memory array having a plurality of separate strapping lines and a plurality of channels connecting the plurality of strapping lines is taught by the Appellant and claimed in claims 5-7. An integrated circuit having such a memory array is claimed in claims 19-25. An information handling device having such a memory array is taught and claimed in claims 30-36 (pg. 5 lines 8-9, pg. 6 lines 14-16, pg. 6 line 20 to pg. 7 line 10).

A memory device having a number of strapping devices is taught by Appellant and claimed in claims 8-14 (pg. 5 lines 8-16 and line 24, and pg. 6 line 20 to pg. 7 line 10). A memory device taught by Appellant and claimed in claims 55-57 includes a number of parallel wordlines local to a memory array coupled to gate regions of memory cells. The even wordlines are coupled to the even row decoder and one or more odd wordlines are coupled to the odd row decoder. The odd wordlines are arranged alternately with the even wordlines. The memory device also includes a number of strapping lines having lower resistance than the wordlines which are connected to bypass portions of the wordlines within the memory array. A strapping line is connected to an odd wordline so that it bypasses only a portion of the odd wordline within the memory array nearer the odd row decoder, and a strapping line is connected to an even wordline so that it bypasses only a portion of the even wordline within the memory array nearer the even row decoder (FIG. 5, pg. 6 lines 4-7, pg. 6 line 20 to pg. 7 line 10, and pg. 8 lines 14-22).

A method of reducing a wordline RC time constant is taught by Appellant and claimed in claims 37-41. The method includes spacing a number of strapping devices over wordlines within a single memory array apart from adjacent strapping devices by a distance greater than a wordline pitch. The strapping devices bypass different portions of adjacent wordlines within the single memory array. A signal is used to bypass a first

portion of the wordline through a strapping device of lower resistance than the first portion of the wordline (FIG. 5, pg. 6 line 20 to pg. 7 line 27).

A method of forming a memory device is taught by Appellant and claimed in claims 45-48. The method includes attaching a strapping line of lower resistance than the wordlines to a single continuous wordline that bypasses only a portion in a middle region between a first and second end of the single continuous wordline. The strapping line bypasses only a portion of a wordline within the memory cell array and bypasses a different portion of a wordline within the memory cell array than an adjacent strapping line (FIG. 5, pg. 6 line 20 to pg. 7 line 10). A method of forming a memory device that includes attaching a number of strapping lines is claimed in claims 49-54.

This summary does not provide an exhaustive or exclusive view of the present subject matter, and Appellants refer to the appended claims and its legal equivalents for a complete statement of the invention.

6. GROUNDS OF REJECTION TO BE REVIEWED ON APPEAL

Claim 1-41 and 45-57 were rejected under 35 U.S.C. § 102(b) for anticipation by Cowles (U.S. 5,940,315).

7. ARGUMENT

Rejections under 35 U.S.C. § 102(b).

1) Applicable Law

A claim is anticipated only if each and every element as set forth in the claim is found, either expressly or inherently described, in a single prior art reference. M.P.E.P. § 2131. To anticipate a claim, a reference must disclose every element of the challenged claim and enable one skilled in the art to make the anticipating subject matter. *PPG Industries, Inc. v. Guardian Industries Corp.*, 75 F.3d 1558, 37 USPQ2d 1618 (Fed. Cir. 1996). The identical invention must be shown in as complete detail as is contained in the claim. *Richardson v. Suzuki Motor Co.*, 868 F.2d 1226, 1236, 9 USPQ2d 1913, 1920 (Fed. Cir. 1989). The elements must be arranged as required by the claim, but this is not an *ipsissimis verbis* test, i.e. identity of terminology is not required. *In re Bond*, 910 F.2d 831, 15 USPQ2d 1566 (Fed. Cir. 1990). Appellant respectfully submits that the Final Office Action mailed January 30, 2006 (hereinafter “the Final Office Action”) did not make out a *prima facie* case of anticipation because Cowles does not teach each and every claim element arranged as in the claims.

A claim in dependent form shall be construed to incorporate by reference all of the limitations of the claim to which it refers. 35 U.S.C. § 112 ¶4. Thus, if a reference does not anticipate a base claim, the reference does not anticipate a claim that depends on the base claim.

2) Discussion of the rejection of claims 1-41 and 45-57 under 35 U.S.C. § 102(b) as anticipated by Cowles(U.S. Pat. No. 5,940,315)

Claims 1-41 and 45-57 were rejected under 35 USC § 102(b) as being anticipated by Cowles (U.S. Patent No. 5,940,315, hereinafter “Cowles”). This rejection is respectfully traversed. Appellant respectfully submits that the Final Office Action has not made a proper *prima facie* showing of anticipation at least because Cowles fails to teach each and every element of claims 1-41 and 45-57.

a. Discussion of the rejection of claims 1-4, 8-14, 15-18, and 26-29

The Final Office Action admits that Cowles does not show “a number of memory cells,” a number of source lines,” or “a number of bit lines” (see Final Office Action page 2 ¶4). As such, the Final Office Action has not made a *prima facie* case of anticipation. The Final Office Action asserts that the missing elements are inherent in Cowles’ teachings, and that by reading any reference cited in the References Cited section of Cowles, one would find all these limitations (see Final Office Action pages 6 and 7). Appellant respectfully submits that the Final Office Action has not established a *prima facie* case of inherency because, as stated in M.P.E.P. § 2131.01, to serve as an anticipation when a reference is silent about the asserted inherent characteristic, the gap in the reference may be filled with recourse to extrinsic evidence. But, such evidence must make clear that “the missing descriptive matter is necessarily present in the thing described in the reference, and that it would be so recognized by persons of ordinary skill.” *Continental Can Co. v. Monsanto Co.*, 20 USPQ2d 1746, 1749 (Fed. Cir. 1991). Appellant respectfully submits that the Examiner has not produced proper extrinsic evidence to show that the elements “a number of memory cells,” “a number of source lines,” and “a number of bit lines” recited in claim 1, 8, 15, and 26 are necessarily present in Cowles.

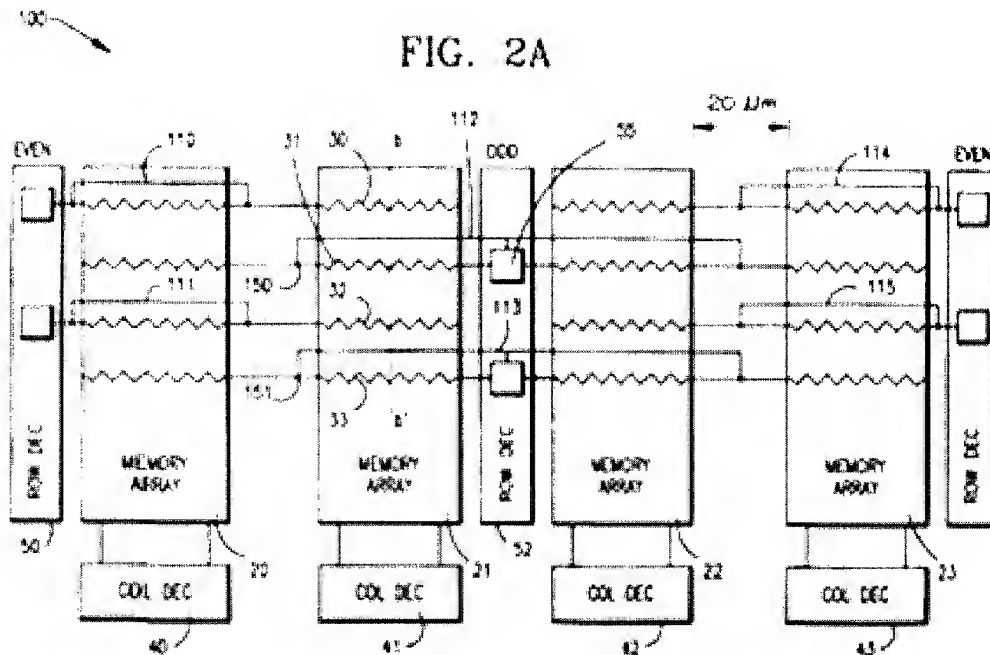
i.) Discussion of claims 1-4

Appellant cannot find in Cowles, among other things,

a strapping line of lower resistance than the wordlines coupled to a single continuous wordline in a single array wherein the strapping line bypasses only a portion in a middle region between a first and second end of the single continuous wordline, wherein the strapping line is spaced apart from adjacent conductive structures by a distance greater than a wordline pitch, and wherein the strapping line bypasses only a portion of a wordline within the single array and bypasses a different portion of a wordline within the single array than an adjacent strapping line,

as recited in claim 1 or incorporated in claims 2-4. The conductive straps of Cowles bypass a wordline across an entire memory array (see e.g., FIG. 2A of Cowles reproduced below), instead of “only a portion of a wordline within the single array” as

recited in claim 1. The Final Office Action asserts that the memory bank 100 of Cowles reads on the single memory array recited in claim 1 (*see* Final Office Action pg. 3), and apparently asserts that because Cowles shows metal straps spanning wordlines of the memory arrays within the memory bank Cowles therefore bypasses a different portion of a wordline within the memory array.



However, the memory bank 100 of Cowles is made of more than one memory array (*see* FIG. 2A), and Cowles states that the invention ... may be used with any number of arrays greater than one (*see* col. 3 lines 23-27). Cowles also states that “[s]traps 112, 113 are connected to wordlines 31, 33 respectively outside the edge of [memory] array 21 as shown in FIG. 2A at nodes 150, 151 through a contact hole in the poly layers” (*see* Cowles, col. 4 lines 2-4). Thus, Cowles does not disclose the structure recited in claim 1.

ii.) Discussion of claims 8-14

Appellant cannot find in Cowles, among other things,

a number of strapping devices which bypass portions of the wordlines in the single array of parallel wordlines, wherein at least one portion of a single continuous wordline is only in a middle region between a first and second end of the single continuous wordline, and wherein adjacent strapping devices bypass only a portion of a wordline within the memory array and bypass different portions of adjacent wordlines within the memory array,

as recited in claim 8 or incorporated in claims 9-14.

iii.) Discussion of claims 15-18

Appellant cannot find in Cowles, among other things,

a strapping line of lower resistance than the wordlines coupled to a single continuous wordline wherein the strapping line bypasses only a portion of the wordline within the memory array in a middle region between a first and second end of the single continuous wordline, wherein the strapping line is spaced apart from adjacent conductive structures by a distance greater than a wordline pitch, and wherein the strapping line bypasses a different portion of a wordline within the memory array than an adjacent strapping line,

as recited in claim 15 or incorporated in claims 16-18.

iv.) Discussion of claims 26-29

Appellant cannot find in Cowles, among other things,

a strapping line of lower resistance than the wordlines coupled to a single continuous wordline wherein the strapping line bypasses only a portion in a middle region between a first and second end of the single continuous wordline and bypasses only a portion of the wordline within the memory array, wherein the strapping line is spaced apart from adjacent conductive structures by a distance greater than a wordline pitch, and wherein the strapping line bypasses a different portion of a wordline within the memory array than an adjacent strapping line,

as recited in claim 26 or incorporated in claims 27-29.

Appellant respectfully requests reconsideration and allowance of claims 1-4, 8-14, 15-18, and 26-29.

b. Discussion of the rejection of claims 5-7, 19-25, 30-36, 37-41, 45-48, and 49-54

i) Discussion of claims 5-7

Appellant cannot find in Cowles, among other things,

a plurality of separate strapping lines of lower resistance than the wordlines coupled to at least one of the number of wordlines in a single array wherein the strapping lines bypass a plurality of separate portions of a single continuous wordline, and wherein adjacent strapping lines bypass only a portion of a wordline within the memory array and bypass different portions of adjacent wordlines within the memory array,

as recited in claim 5 or incorporated in claims 6-7. The conductive straps of Cowles bypass a wordline across an entire memory array (see e.g., FIG. 2A), instead of “only a portion of a wordline within the memory array” as recited in claim 5. An example of strapping lines bypassing only a portion of the wordlines within a memory is shown in FIG. 5 of the present application (reproduced below).

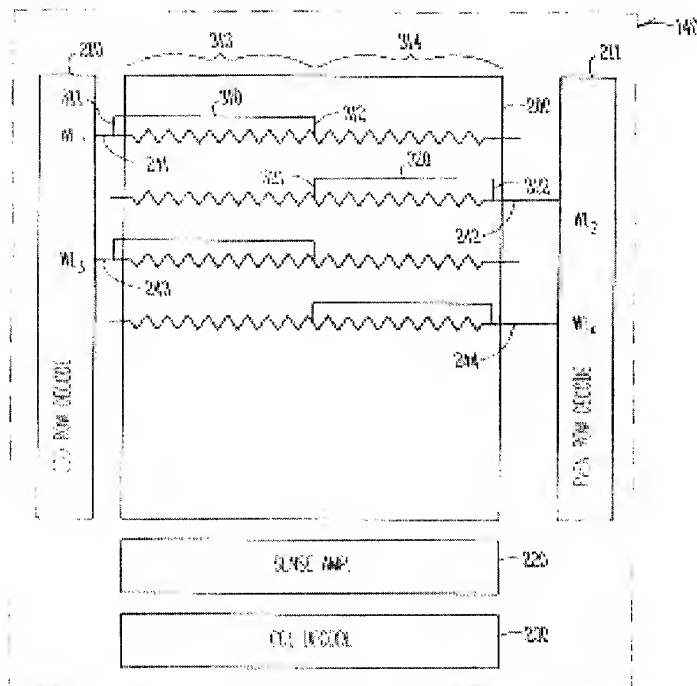


Fig. 5

The memory bank 100 of Cowles is made of more than one memory array (*see* FIG. 2A), and Cowles states that the invention ... may be used with any number of arrays greater than one (*see* col. 3 lines 23-27). Cowles also states that “[s]traps 112, 113 are connected to wordlines 31, 33 respectively outside the edge of [memory] array 21 as shown in FIG. 2A at nodes 150, 151 through a contact hole in the poly layers” (*see* Cowles, col. 4 lines 2-4). Thus, Cowles does not disclose the structure recited in claim 5. For example, Cowles does not contain any disclosure of “wherein adjacent strapping lines bypass only a portion of a wordline within the memory array”, or any disclosure of “[wherein adjacent strapping lines] bypass different portions of adjacent wordlines within the memory array,” as recited in claim 5.

ii) Discussion of claims 19-25

Appellant cannot find in Cowles, among other things,

a number of separate strapping devices which bypass separate portions of a single continuous wordline in the single array of parallel wordlines, and wherein adjacent strapping devices bypass only a portion of a wordline within the memory array and bypass different portions of adjacent wordlines within the single array,

as recited in claim 19 or incorporated in claims 20-25.

iii) Discussion of claims 30-36

Appellant cannot find in Cowles, among other things,

a number of strapping devices which bypass only portions of the wordlines in the single array of parallel wordlines, wherein at least one portion of a single continuous wordline is in a middle region between a first and second end of the single continuous wordline, and wherein adjacent strapping devices bypass only a portion of the wordline within the memory array and bypass different portions of adjacent wordlines within the memory array,

as recited in claim 30 or incorporated in claims 31-36.

iv) Discussion of claims 37-41

Appellant cannot find in Cowles, among other things,

spacing a number of strapping devices over wordlines within a single memory array apart from adjacent strapping devices by a distance greater than a wordline pitch, wherein adjacent strapping devices bypass different portions of adjacent wordlines within the single memory array,

as recited in claim 37 or incorporated in claims 38-41.

v) Discussion of claims 45-48

Appellant cannot find in Cowles, among other things,

attaching a strapping line of lower resistance than the wordlines to a single continuous wordline wherein the strapping line bypasses only a portion in a middle region between a first and second end of the single continuous wordline, wherein the strapping line is spaced apart from adjacent conductive structures by a spacing greater than a wordline pitch and wherein the strapping line bypasses only a portion of a wordline within the memory cell array and bypasses a different portion of a wordline within the memory cell array than an adjacent strapping line,

as recited in claim 45 or incorporated in claims 46-48.

vi) Discussion of claims 49-54

Appellant cannot find in Cowles, among other things,

attaching a number of strapping lines of lower resistance than the wordlines which bypass portions of the wordlines in the array of parallel wordlines, wherein at least one portion of a single continuous wordline is only in a middle region between a first and second end of the single continuous wordline, wherein the strapping lines are each located a distance from each other that is greater than the pitch, and wherein adjacent strapping lines bypass different portions of adjacent wordlines within the single array,

as recited in claim 49 or incorporated in claims 50-54.

Appellant respectfully requests reconsideration and allowance of claims 5-7, 19-25, 30-36, 37-41, 45-48, and 49-54.

c. Discussion of the rejection of claims 55-57

Appellant cannot find in Cowles, among other things,

a number of strapping lines having lower resistance than the wordlines and connected to bypass portions of the wordlines within the memory array, wherein a strapping line connected to an odd wordline bypasses only a portion of the odd wordline within the memory array nearer the odd row decoder, wherein a strapping line connected to an even wordline bypasses only a portion of the even wordline within the memory array nearer the even row decoder,

as recited in claim 55 or incorporated in claims 56-57.

The conductive straps of Cowles bypass a wordline across an entire memory array (see e.g., FIG. 2A), instead of only “portions of the wordlines within the memory array” as recited in claim 55. The memory bank 100 of Cowles is made of more than one memory array (see FIG. 2A), and Cowles states that the invention ... may be used with any number of arrays greater than one (see col. 3 lines 23-27). Cowles also states that “[s]traps 112, 113 are connected to wordlines 31, 33 respectively outside the edge of [memory] array 21 as shown in FIG. 2A at nodes 150, 151 through a contact hole in the poly layers” (see Cowles, col. 4 lines 2-4). Thus, Cowles does not disclose the structure recited in claim 55.

Claim 55 also recites

an even row decoder located on a first side of the memory array, an odd row decoder located on a second side of the memory array, ... wherein a strapping line connected to an odd wordline bypasses only a portion of the odd wordline within the memory array nearer the odd row decoder, wherein a strapping line connected to an even wordline bypasses only a portion of the even wordline within the memory array nearer the even row decoder.

Cowles describes,

“[r]ow decoders 50 and 54 are designated as even row decoders, and row decoder 52 is designated as an odd row decoder. Row decoder 50 is positioned adjacent to memory array 20 on the opposite side of memory array 21, row decoder 52 is positioned between memory array 21 and memory array 22 and row decoder 54 is positioned adjacent to memory array 23 on the opposite side of memory array 22 as shown”

(see Cowles, FIG. 2A and col. 3 lines 39-46). Thus, Cowles refers to an arrangement where an even row decoder is on one side of two memory arrays and an odd row decoder is on an opposite side of the two memory arrays, and therefore Cowles does not describe the structure recited in claim 55.

Appellant respectfully requests reconsideration and allowance of claims 55-57.

d. Conclusion

Appellant respectfully submits that the *prima facie* case of anticipation is improper because each and every element as set forth in the claims is not found, either expressly or inherently described, in Cowles. Therefore, Appellant requests reversal of the 35 U.S.C. § 102(b) rejection and allowance of claims 1-41 and 45-57.

8. SUMMARY

It is respectfully submitted that a *prima facie* case of anticipation under 35 U.S.C. § 102(b) has not been established. Therefore, it is respectfully requested that the rejection of Claims 1-41 and 45-57 be overturned. Appellant further submits that the claims are in condition for allowance and notification to that effect is earnestly requested. The Examiner is invited to contact Appellant's Attorney, Timothy B. Clise, at (612) 349-9587, if prosecution will be assisted thereby.

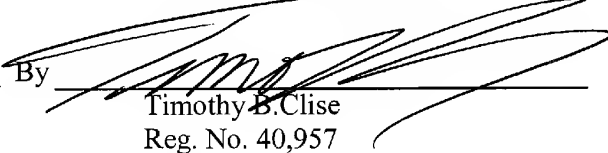
Respectfully submitted,

HUY T. VO

By his Representatives,,
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Date 9 OCT '06 By 
Timothy B. Clise
Reg. No. 40,957

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being filed using the USPTO's electronic filing system EFS-Web, and is addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 9 day of October, 2006.

Kate Gannon
Name


Signature

CLAIMS APPENDIX

1. A memory array, comprising:
 - a number of memory cells having a first source/drain region and a second source/drain region and a gate region;
 - a number of source lines coupled to the first source/drain region of at least one memory cell;
 - a number of bit lines coupled to the second source/drain region of at least one memory cell;
 - a number of wordlines coupled to the gate region of at least one memory cell;
 - a strapping line of lower resistance than the wordlines coupled to a single continuous wordline in a single array, wherein the strapping line bypasses only a portion in a middle region between a first and second end of the single continuous wordline, wherein the strapping line is spaced apart from adjacent conductive structures by a distance greater than a wordline pitch, and wherein the strapping line bypasses only a portion of a wordline within the single memory array and bypasses a different portion of a wordline within the single array than an adjacent strapping line; and
 - at least two channels connecting the strapping line to a first and second end of the portion of the single continuous wordline.
2. The memory array of claim 1 wherein the strapping line comprises metal.
3. The memory array of claim 2 wherein the metal comprises a refractory metal.
4. The memory array of claim 1 wherein the portion of the wordline bypassed by the strapping line comprises a first half of the memory cells coupled to the wordline.

5. A memory array, comprising:
 - a number of memory cells having a first source/drain region and a second source/drain region and a gate region;
 - a number of source lines coupled to the first source/drain region of at least one memory cell;
 - a number of bit lines coupled to the second source/drain region of at least one memory cell;
 - a number of wordlines coupled to the gate region of at least one memory cell;
 - a plurality of separate strapping lines of lower resistance than the wordlines coupled to at least one of the number of wordlines in a single array wherein the strapping lines bypass a plurality of separate portions of a single continuous wordline, and wherein adjacent strapping lines bypass only a portion of a wordline within the memory array and bypass different portions of adjacent wordlines within the memory array; and
 - a plurality of channels connecting the plurality of strapping layers to the wordline.
6. The memory array of claim 5 wherein the plurality of strapping lines comprise metal.
7. The memory array of claim 6 wherein the metal comprises a refractory metal.
8. A memory device, comprising:
 - a number of memory cells having a first source/drain region and a second source/drain region and a gate region, the memory cells forming a memory cell array;
 - a number of source lines coupled to the first source/drain region of at least one memory cell;
 - a number of bit lines coupled to the second source/drain region of at least one memory cell;
 - a single array of parallel wordlines coupled to the gate region of at least one memory cell, the array of parallel wordlines having a pitch;

a number of strapping devices which bypass portions of the wordlines in the single array of parallel wordlines, wherein at least one portion of a single continuous wordline is only in a middle region between a first and second end of the single continuous wordline, and wherein adjacent strapping devices bypass only a portion of a wordline within the memory array and bypass different portions of adjacent wordlines within the memory array, each strapping device comprising:

a strapping line of lower resistance than the wordlines, wherein the strapping lines are each located a distance from each other that is greater than the pitch; and

at least two channels connecting each strapping line to a portion of a single wordline.

9. The memory device of claim 8 wherein the strapping line comprises metal.

10. The memory device of claim 9 wherein the metal comprises a refractory metal.

11. The memory device of claim 8 wherein the portions of the wordlines in the array bypassed by the number of strapping devices comprises a plurality of end portions of the wordlines.

12. The memory device of claim 8 wherein the strapping devices are located on alternating wordlines in the array.

13. The memory device of claim 8 wherein the strapping devices are located on adjacent wordlines and staggered along the wordlines such that the portions of the adjacent wordlines that are bypassed are not adjacent to each other.

14. The memory device of claim 8 wherein the strapping devices strap a first half portion of a number of even wordlines in the array and a second half portion of a number of odd wordlines.

-
15. An integrated circuit comprising:
 - at least one memory array comprising:
 - a number of memory cells having a first source/drain region and a second source/drain region and a gate region;
 - a number of source lines coupled to the first source/drain region of at least one memory cell;
 - a number of bit lines coupled to the second source/drain region of at least one memory cell;
 - a number of wordlines in a single array coupled to the gate region of at least one memory cell;
 - a strapping line of lower resistance than the wordlines coupled to a single continuous wordline wherein the strapping line bypasses only a portion of the wordline within the memory array in a middle region between a first and second end of the single continuous wordline, wherein the strapping line is spaced apart from adjacent conductive structures by a distance greater than a wordline pitch, and wherein the strapping line bypasses a different portion of a wordline within the memory array than an adjacent strapping line;
 - at least two channels connecting the strapping line to a first and second end of the portion of the single continuous wordline;
 - a row decoder;
 - a column decoder; and
 - a sense amplifier.
 16. The integrated circuit of claim 15 wherein the strapping line comprises metal.
 17. The integrated circuit of claim 16 wherein the metal comprises a refractory metal.
 18. The integrated circuit of claim 15 wherein the portion of the wordline bypassed by the strapping line comprises a first half of the memory cells coupled to the wordline.

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19. An integrated circuit comprising:
 - at least one memory array comprising:
 - a number of memory cells having a first source/drain region and a second source/drain region and a gate region;
 - a number of source lines coupled to the first source/drain region of at least one memory cell;
 - a number of bit lines coupled to the second source/drain region of at least one memory cell;
 - a single array of parallel wordlines coupled to the gate region of at least one memory cell, the array of parallel wordlines having a pitch;
 - a number of separate strapping devices which bypass separate portions of a single continuous wordline in the single array of parallel wordlines, and wherein adjacent strapping devices bypass only a portion of a wordline within the memory array and bypass different portions of adjacent wordlines within the single array, each strapping device comprising:
 - a strapping line of lower resistance than the wordlines, wherein the strapping lines are each located a distance from each other that is greater than the pitch;
 - at least two channels connecting the strapping line to the single continuous wordline;
 - a row decoder;
 - a column decoder; and
 - a sense amplifier.
 20. The integrated circuit of claim 19 wherein the strapping line comprises metal.
 21. The integrated circuit of claim 20 wherein the metal comprises a refractory metal.
 22. The integrated circuit of claim 19 wherein the portions of the wordlines in the array bypassed by the number of strapping devices comprises a plurality of end portions of the wordlines.

23. The integrated circuit of claim 19 wherein the strapping devices are located on alternating wordlines in the array.

24. The integrated circuit of claim 19 wherein the strapping devices are located on adjacent wordlines and staggered along the wordlines such that the portions of the adjacent wordlines that are bypassed are not adjacent to each other.

25. The integrated circuit of claim 19 wherein the strapping devices strap a first half portion of a number of even wordlines in the array and a second half portion of a number of odd wordlines.

26. An information handling device comprising:

a processing unit;

at least one memory array comprising:

a number of memory cells having a first source/drain region and a second source/drain region and a gate region;

a number of source lines coupled to the first source/drain region of at least one memory cell;

a number of bit lines coupled to the second source/drain region of at least one memory cell;

a number of wordlines in a single array coupled to the gate region of at least one memory cell;

a strapping line of lower resistance than the wordlines coupled to a single continuous wordline wherein the strapping line bypasses only a portion in a middle region between a first and second end of the single continuous wordline and bypasses only a portion of the wordline within the memory array, wherein the strapping line is spaced apart from adjacent conductive structures by a distance greater than a wordline pitch, and wherein the strapping line bypasses a different portion of a wordline within the memory array than an adjacent strapping line;

at least two channels connecting the strapping line to the single continuous wordline; and

a system bus connecting the processing unit to the memory array.

27. The information handling device of claim 26 wherein the strapping line comprises metal.

28. The information handling device of claim 27 wherein the metal comprises a refractory metal.

29. The information handling device of claim 26 wherein the portion of the wordline bypassed by the strapping line comprises a first half of the memory cells coupled to the wordline.

30. An information handling device comprising:

a processing unit;

at least one memory array comprising:

a number of memory cells having a first source/drain region and a second source/drain region and a gate region;

a number of source lines coupled to the first source/drain region of at least one memory cell;

a number of bit lines coupled to the second source/drain region of at least one memory cell;

a single array of parallel wordlines coupled to the gate region of at least one memory cell, the array of parallel wordlines having a pitch;

a number of strapping devices which bypass only portions of the wordlines in the single array of parallel wordlines, wherein at least one portion of a single continuous wordline is in a middle region between a first and second end of the single continuous wordline, and wherein adjacent strapping devices bypass only a portion of the wordline within the memory array and bypass different portions of adjacent wordlines within the memory array, each strapping device comprising:

a strapping line of lower resistance than the wordlines, wherein the strapping lines are each located a distance from each other that is greater than the pitch; and
 at least two channels connecting each strapping line to single wordlines;
 and
 a system bus connecting the processing unit to the memory array.

31. The information handling device of claim 30 wherein the strapping line comprises metal.

32. The information handling device of claim 31 wherein the metal comprises a refractory metal.

33. The information handling device of claim 30 wherein the portions of the wordlines in the array bypassed by the number of strapping devices comprises a plurality of end portions of the wordlines.

34. The information handling device of claim 30 wherein the strapping devices are located on alternating wordlines in the array.

35. The information handling device of claim 30 wherein the strapping devices are located on adjacent wordlines and staggered along the wordlines such that the portions of the adjacent wordlines that are bypassed are not adjacent to each other.

36. The information handling device of claim 30 wherein the strapping devices strap a first half portion of a number of even wordlines in the array and a second half portion of a number of odd wordlines.

37. A method of reducing a wordline RC time constant comprising:
 spacing a number of strapping devices over wordlines within a single memory array apart from adjacent strapping devices by a distance greater than a wordline pitch, wherein adjacent

strapping devices bypass different portions of adjacent wordlines within the single memory array;

connecting individual strapping devices to portions in a middle region between a first and second end of single continuous wordlines using at least two channels for each strapping device;

activating a first number of transistors coupled to a first portion of a wordline; and

activating a second number of transistors coupled to a second portion of a wordline, wherein a signal used for activating the second number of transistors bypasses the first portion of the wordline through a strapping device of lower resistance than the first portion of the wordline;

activating a selected bitline in the memory array associated with a selected memory cell;

discharging the selected memory cell through a selected transistor, the selected transistor being activated by both the selected row and the selected bitline; and

sensing the presence or absence of a charge from the selected memory cell through the use of a sense amplifier.

38. The method of reducing a wordline RC time constant of claim 37, wherein activating a second number of transistors coupled to a second portion of a wordline comprises:

sending a signal through a first channel to a metal strapping line;

sending the signal through the metal strapping line; and

sending the signal through a second channel to the second portion of the wordline.

39. The method of reducing a wordline RC time constant of claim 38, wherein sending the signal through the metal strapping line comprises sending the signal through a refractory metal strapping line.

40. The method of reducing a wordline RC time constant of claim 37, wherein activating a first number of transistors coupled to a first portion of a wordline comprises activating a first number of transistors coupled to a first half of the wordline.

41. The method of reducing a wordline RC time constant of claim 37, wherein activating a selected row in a memory array comprises bypassing multiple portions of the wordline using multiple strapping devices of lower resistance than the wordline.

45. A method of forming a memory device comprising:

forming a number of memory cells having a first source/drain region and a second source/drain region and a gate region, the memory cells forming a memory cell array;

coupling a number of source lines to the first source/drain region of at least one memory cell;

coupling a number of bit lines to the second source/drain region of at least one memory cell;

attaching a number of wordlines to the gate region of at least one memory cell to form a single array;

attaching a strapping line of lower resistance than the wordlines to a single continuous wordline wherein the strapping line bypasses only a portion in a middle region between a first and second end of the single continuous wordline, wherein the strapping line is spaced apart from adjacent conductive structures by a spacing greater than a wordline pitch and wherein the strapping line bypasses only a portion of a wordline within the memory cell array and bypasses a different portion of a wordline within the memory cell array than an adjacent strapping line; and

connecting the strapping line to the single wordline by forming at least two channels from the strapping line to the single continuous wordline.

46. The method of forming a memory device of claim 45, wherein attaching at least one strapping line of lower resistance than the wordlines to at least one of the number of wordlines comprises attaching at least one metal strapping line.

47. The method of forming a memory device of claim 46, wherein attaching at least one metal strapping line comprises attaching at least one refractory metal strapping line.

48. The method of forming a memory device of claim 45, wherein attaching at least one strapping line of lower resistance than the wordlines to at least one of the number of wordlines comprises attaching multiple strapping lines to bypass multiple portions of a single wordline.

49. A method of forming a memory device comprising:

forming a number of memory cells having a first source/drain region and a second source/drain region and a gate region, the memory cells forming a memory cell array;

coupling a number of source lines coupled to the first source/drain region of at least one memory cell;

coupling a number of bit lines coupled to the second source/drain region of at least one memory cell;

attaching a single array of parallel wordlines to the gate region of at least one memory cell, the single array of parallel wordlines having a pitch;

attaching a number of strapping lines of lower resistance than the wordlines which bypass portions of the wordlines in the array of parallel wordlines and bypass only a portion of a wordline within the memory cell array and, wherein at least one portion of a single continuous wordline is only in a middle region between a first and second end of the single continuous wordline, wherein the strapping lines are each located a distance from each other that is greater than the pitch, and wherein adjacent strapping lines bypass different portions of adjacent wordlines within the memory cell array; and

connecting the strapping lines to the wordlines by forming at least two channels from each strapping line to individual wordlines.

50. The method of forming a memory device of claim 49, wherein attaching a number of strapping lines comprises attaching a number of metal strapping lines.

51. The method of forming a memory device of claim 50, wherein attaching a number of metal strapping lines comprises attaching a number of refractory metal strapping lines.

52. The method of forming a memory device of claim 49, wherein attaching a number of strapping lines comprises attaching the strapping lines on alternating wordlines in the array.

53. The method of forming a memory device of claim 49, wherein attaching the strapping lines comprises attaching the strapping lines on adjacent wordlines and staggering the strapping lines along the wordlines such that the portions of the adjacent wordlines that are bypassed are not adjacent to each other.

54. The method of forming a memory device of claim 49, wherein attaching a number of strapping lines comprises attaching the strapping lines on a first half portion of a number of even wordlines in the array and attaching the strapping lines on a second half portion of a number of odd wordlines.

55. A memory device comprising:

- a memory array including a number of memory cells;
- an even row decoder located on a first side of the memory array;
- an odd row decoder located on a second side of the memory array;
- a single column decoder connected to the memory array;
- a number of parallel wordlines local to the memory array coupled to gate regions of memory cells, including one or more even wordlines coupled to the even row decoder, and one or more odd wordlines coupled to the odd row decoder, the odd wordlines arranged alternately with the even wordlines; and
- a number of strapping lines having lower resistance than the wordlines and connected to bypass portions of the wordlines within the memory array, wherein a strapping line connected to an odd wordline bypasses only a portion of the odd wordline within the memory array nearer the odd row decoder, wherein a strapping line connected to an even wordline bypasses only a portion of the even wordline within the memory array nearer the even row decoder.

56. The memory device of claim 55, wherein the even row decoder is located directly adjacent the first side and the odd row decoder is located directly adjacent the second side.

57. The memory device of claim 55, wherein a strapping line connected to an odd wordline bypasses only one half of the wordline within the memory array nearer the odd row decoder and a strapping line connected to an even wordline bypasses only one half of the wordline within the memory array nearer the even row decoder.

EVIDENCE APPENDIX

None.

RELATED PROCEEDINGS APPENDIX

None.